

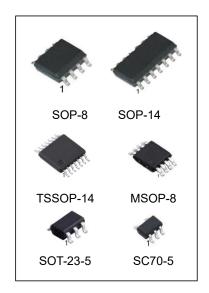


# 11MHZ CMOS Rail-to-Rail IO Opamps

#### Features

- Single-Supply Operation from +2.1V ~ +5.5V
- Rail-to-Rail Input / Output
- Gain-Bandwidth Product: 11MHz (Typ.)
- Low Input Bias Current: 1pA (Typ.)
- Low Offset Voltage: 3.5mV (Max.)
- High Slew Rate: 9V/µs
- Settling Time to 0.1% with 2V Step: 0.3µs
- Low Noise : 8nV/ Hz @10kHz
- Quiescent Current: 1.1mA per Amplifier (Typ.)
- Operating Temperature: -40°C ~ +85°C
- Small Package: HGV6021 Available in SOT23-5,MSOP-8 and SC70-5 Packages HGV6022 Available in SOP-8 and MSOP-8 Packages HGV6024 Available in SOP-14 and TSSOP-14 Packages

## Package/Ordering Information



DEVICE	Package Type	MARKING	Packing	Packing Qty
HGV6021M5/TR	SOT-23-5	6021	REEL	3000pcs/reel
HGV6021M7/TR	SC70-5(SOT-353)	6021	REEL	3000pcs/reel
HGV6021M/TR	SOP-8	V6021	REEL	2500pcs/reel
HGV6021MM/TR	MSOP-8	V6021	REEL	3000pcs/reel
HGV6022M/TR	SOP-8	V6022	REEL	2500pcs/reel
HGV6022MM/TR	MSOP-8	V6022	REEL	3000pcs/reel
HGV6024M/TR	SOP-14	HGV6024	REEL	2500pcs/reel
HGV6024MT/TR	TSSOP-14	V6024	REEL	2500pcs/reel



## **General Description**

The HGV602X have a high gain-bandwidth product of 11MHz, a slew rate of 9Vµ/s, and a quiescent current of 1.1mA peramplifier at 5V. The HGV602X are designed to provideoptimal performance in low voltage and low noise systems. They provide rail-to-rail output swing into heavy loads. The input common mode voltage range includes ground, and the maximum input offset voltage is 3.5mV for HGV602X. They are specified over the extended industrial temperature range (-40 °C to +85 °C ). The operating range is from 2.1V to 5.5V. The HGV6021 sin gle is available in Green SC70-5, SOT-23-5,MSOP-8 and SOP-8 packages. The HGV6022 dual is available in Green SOP-8 and MSOP-8 pa ckages. The HGV6024 Quad is available in Green SOP-14 and TSSOP-14 packages.

### Applications

- Sensors
- Active Filters
- Cellular and Cordless Phones
- Laptops and PDAs
- Audio
- Handheld Test Equipment
- Battery-Powered Instrumentation
- A/D Converters



## **Pin Configuration**

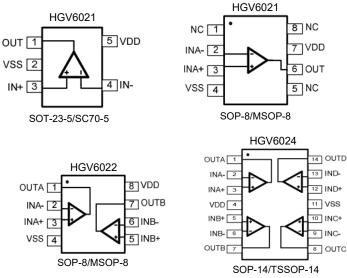


Figure 1. Pin Assignment Diagram

#### **Absolute Maximum Ratings**

Condition	Min	Max			
Power Supply Voltage (VDD to Vss)	-0.5V	+7.5V			
Analog Input Voltage (IN+ or IN-)	Vss-0.5V	VDD+0.5V			
PDB Input Voltage	Vss-0.5V	+7V			
Operating Temperature Range	-40°C	+85 °C			
Junction Temperature	+16	0°C			
Storage Temperature Range	-55°C	+150°C			
Lead Temperature (soldering, 10sec)	+24	5°C			
Package Thermal Resistance (TA=+25℃)					
SOP-8, θJA	125°	125°C/W			
MSOP-8, θJA	216°	°C/W			
SOT-23-5, θJA	190°	°C/W			
SOT23-6, θJA	190°	°C/W			
SC70-5, 0JA	333°	°C/W			
ESD Susceptibility					
НВМ	8KV				
ММ	400V				

#### Note:

Stress greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is astress rating only and functional operation of the device at these or any other conditions outside those indicated in the operationalsections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affectreliability.



## **Electrical Characteristics**

(At Vs=5V, TA = +25℃, VCM =	= VS/2, RL = 600Ω	, unless otherwise noted.)
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				HGV60	21/2/4		
	CONDITIONS	ТҮР	MIN	MAX OV	ER TEM	PERATU	RE
PARAMETER	CONDITIONS	<b>+25</b> ℃	<b>+25</b> ℃	0℃ to 70℃	-40℃ to 85℃	UNITS	MIN / MAX
	INPUT CHARACTERIS	TICS			-		
Input Offset Voltage (VOS)		0.8	3.5	3.9	4.3	mV	MAX
Input Bias Current (IB)		1				pА	ТҮР
Input Offset Current (IOS)		1				рΑ	ТҮР
Input Common Mode Voltage Range (VCM)	VS = 5.5V	-0.1 to				v	ТҮР
		+5.6					
Common Mode Rejection Ratio (CMRR)	VS = 5.5V, VCM = -0.1V to 4V	82	65	64	64	dB	MIN
	VS = 5.5V, VCM = -0.1V to 5.6V	75				dB	MIN
Open-Loop Voltage Gain (AOL)	RL = 600Ω,VO = 0.15V to 4.85V	90	80	76	75	dB	MIN
	RL = 10kΩ,VO = 0.05V to 4.95V	108				dB	MIN
Input Offset Voltage Drift (ΔVOS/T)		2.4				µV/℃	ТҮР
OUTPUT CHARACTERISTICS							
Output Voltage Swing from Rail	RL = 600Ω	0.1				V	TYP
	$R_L = 10k\Omega$	0.015				V	ТҮР
Output Current (IOUT)		70	55	45	42	mA	MIN
Closed-Loop Output Impedance	f = 100kHz, G = 1	7.5				Ω	ТҮР
POWER-DOWN DISABLE					•		
Turn-On Time		1.1				μs	ТҮР
Turn-Off Time		0.3				μs	TYP
DISABLE Voltage-Off			0.8			μsV	MAX
DISABLE Voltage-On			2			V	MAX
POWER SUPPLY							
Operating Voltage Range			2.1 5.5	2.1 5.5	2.1 5.5	V V	MIN MAX
Power Supply Rejection Ratio							
(PSRR)	VS = +2.5V to +5.5V	01	<u> </u>				
	VCM =(-VS) + 0.5	91 1.1	74 1 F	72	72	dB	MIN
Quiescent Current/Amplifier (IQ)	V IOUT = 0	1.1	1.5	1.65	1.7	mA	MAX



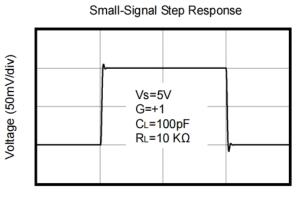
## **Electrical Characteristics**

		HGV6021/2/4								
DADAMETED	CONDITIONS	ТҮР		MIN/MAX (	OVER TEMPE	RATURE				
PARAMETER	CONDITIONS	+25℃		0℃to 70℃	-40 °C to 85 °C	UNITS	MIN / MAX			
	DYNAMIC PEF	FORMA	NCE							
Gain-Bandwidth Product (GBP)	RL = 10kΩ, CL = 100pF	11				MHz	TYP			
Phase Margin (φO)	RL = 10kΩ, CL = 100pF	51				Degrees	TYP			
Full Power Bandwidth (BWP)	$<$ 1% distortion, RL = 600 $\Omega$	400				kHz	TYP			
Slew Rate (SR)	G = +1, 2V Step, RL = 10kΩ	9				V/µs	TYP			
Settling Time to 0.1% (tS)	G = +1, 2V Step, RL = 600Ω	0.3				μs	TYP			
Overload Recovery Time	VIN $\cdot$ Gain = VS, RL = 600 $\Omega$	1.5				μs	TYP			
	NOISE PERF	ORMAN	CE							
Voltage Noise Density (e <sub>n</sub> )	f = 1kHz	11.5				$nV / \sqrt{Hz}$	TYP			
	f = 10kHz	8				$nV / \sqrt{Hz}$	TYP			



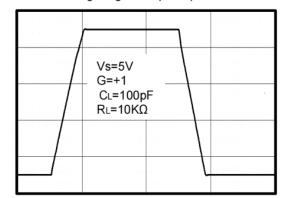
## **Typical Performance characteristics**

(At Vs=5V, TA = +25  $^\circ\!\mathrm{C}$  , VCM = VS/2, RL = 600 $\Omega$ , unless otherwise noted.)

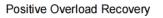


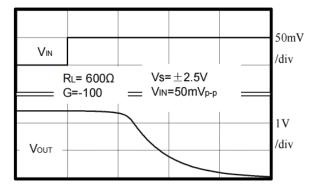


Large-Signal Step Response

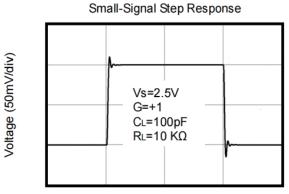


Time (1µs/div)

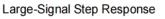


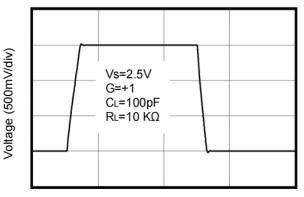


Time (2µs/div)



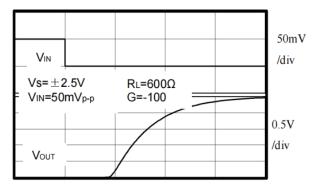
Time (1µs/div)





Time (1µs/div)



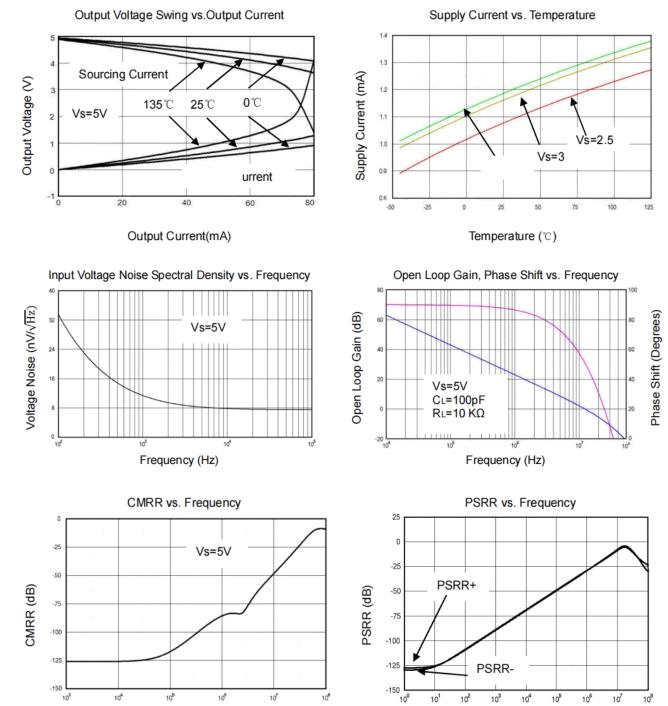


Time (2µs/div)



#### **Typical Performance characteristics**

(At Vs=5V, TA = +25  $^\circ\!\mathrm{C}$  , VCM = VS/2, RL = 600 $\Omega$ , unless otherwise noted.)



Frequency (Hz)

Frequency (Hz)



## **Application Note**

#### Size

HGV602X series op amps are unity-gain stable and sutai ble for a wide range of general-purpose applications. The small footprints of the HGv602X series packages save spaceon printed circuit boards and enable the design of smaller electronic products.

### Power Supply Bypassing and Board Layout

HGV602X series operates from a single 2.1V to 5.5V supply or dual  $\pm 1.05V$  to  $\pm 2.75V$  supplies. For best performance, a 0.1µF ceramic capacitor should be placed close to the VDD pin in single supply operation. For dual supply operation, both VDD and VSS supplies should be bypassed to ground with separate 0.1µF ceramic capacitors.

### Low Supply Current

The low supply current (typical 1.1mA per channel) of HGV602X series will help to maximize battery lif.eThey are ideal for battery powered systems

## **Operating Voltage**

HGV602X series operate under wide input supply voltage (2.1V to 5.5V). In addition, all temperature speci fications apply from-40 °C to +85 °C. Most behavior remains unchanged throughout the full operating voltage range. These guarantees ensure operation throughout the single Li-lon battery lifetime

#### **Rail-to-Rail Input**

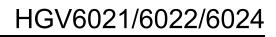
The input common-mode range of HGV602X series extends 100mV beyond the supply rails (VSS-0.1V to VDD+0.1V). This is achieved by using complementary input stage. For normal operation, inputs should be limited to this range.

### Rail-to-Rail Output

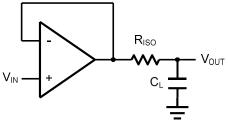
Rail-to-Rail output swing provides maximum possible dynamic range at the output. This is particularly important when operating in low supply voltages. The output voltage of HGV602X series can typically swing to less than2mV from supply rail in light resistive loads (>100k $\Omega$ ), and 15mV of supply rail in moderate resistive loads (10k $\Omega$ ).

### **Capacitive Load Tolerance**

The HGV602X family is optimized for bandwidth and speed, not for driving capacitive loads. Output capacitance will create a pole in the amplifier's feedback path, leading to excessive peaking and potential oscillation. If dealing with load capacitance is a requirement of the application, the two strategies to consider are (1) using a small resistor in series with the amplifier's output and the load capacitance and (2) reducing the bandwidth of the amplifier's feedback loop by increasing the overall noise gain. Figure 2. shows a unity gain follower using the series resistor strategy. The resistor isolates the output from the capacitanceand, more importantly, creates a zero in the feedback path that compensates for the pole created by the output capacitance.







#### Figure 2. Indirectly Driving a Capacitive Load Using Isolation Resistor

The bigger the RISO resistor value, the more stable VOUT will be. However, if there is a resistive load RL in parallel with the capacitive load, a voltage divider (proportional to RISO/RL) is formed, this will result in a gain error.

The circuit in Figure 3 is an improvement to the one in Figure 2. RF provides the DC accuracy by feed-forward the VIN to RL. CFand RISO serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving the phase margin in the overall feedback loop. Capacitive drive can be increased by increasing the value of CF. This in turn will slow down the pulse response.

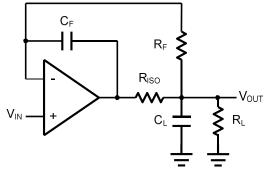
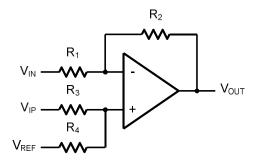


Figure 3. Indirectly Driving a Capacitive Load with DC Accuracy

#### **Typical Application Circuits**

#### **Differential amplifier**

The differential amplifier allows the subtraction of two input voltages or cancellation of a signal common the two inputs. It is useful as a computational amplifier in making a differential to single-end conversion or in rejecting a common mode signal. Figure 4. shown the differential amplifier using HGV602X.



**Figure 4. Differential Amplifier** 

$$V_{\text{OUT}} = \left(\frac{R+R_2}{R+R_4}\right) \frac{R_4}{R} V_{\text{IN}} - \frac{R_2}{R} V_{\text{IP}} + \left(\frac{R+R_2}{R+R_4}\right) \frac{R_2}{R} V_{\text{REF}}$$

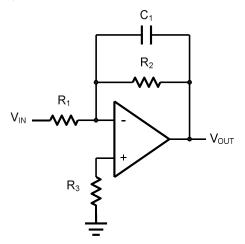
If the resistor ratios are equal (i.e.  $R_1=R_3$  and  $R_2=R_4$ ), then

$$V_{\rm OUT} = \frac{R_2}{R_1} (V_{\rm IP} - V_{\rm IN}) + V_{\rm REF}$$



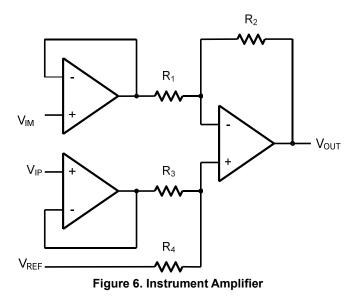
#### Low Pass Active Filter

The low pass active filter is shown in Figure 5. The DC gain is defined by -R2/R1. The filter has a -20dB/decade roll-off after its corner frequency  $fC=1/(2\pi R3C1)$ .



#### **Instrumentation Amplifier**

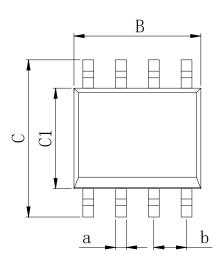
The triple HGV602X can be used to build a three-op-ma p instrumentation amplifier as shown in Figure 6. The amplifier in Figure 6 is a high input impedance differential amplifier with gain of R2/R1. The two differential voltage followers assure the high input impedance of the amplifier.

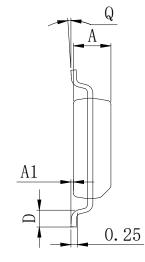




## **Physical Dimensions**

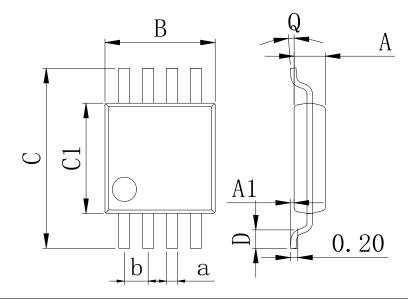
SOP-8





Dimensions In Millimeters(SOP-8)											
Symbol:	A	A1	В	С	C1	D	Q	а	b		
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1 07 000		
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	- 1.27 BSC		

#### MSOP-8



Dimensions In Millimeters(MSOP-8)											
Symbol:	A	A1	В	С	C1	D	Q	а	b		
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC		
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	0.00 030		

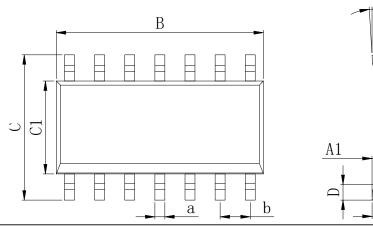


Q

0.25

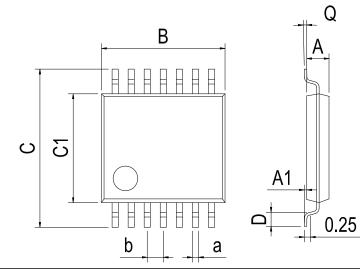
## **Physical Dimensions**

SOP-14



Dimensions In Millimeters(SOP-14)											
Symbol:	A	A1	В	С	C1	D	Q	а	b		
Min:	1.35	0.05	8.55	5.80	3.80	0.40	0°	0.35	1.27 BSC		
Max:	1.55	0.20	8.75	6.20	4.00	0.80	8°	0.45	1.27 030		

TSSOP-14

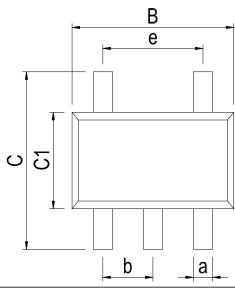


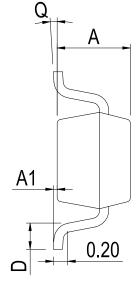
Dimensions In Millimeters(TSSOP-14)											
Symbol:	А	A1	В	С	C1	D	Q	а	b		
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC		
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	0.05 BSC		



## **Physical Dimensions**

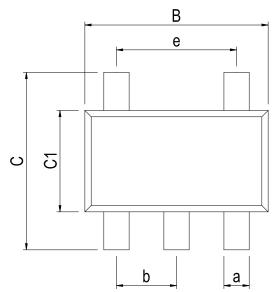
SOT-23-5

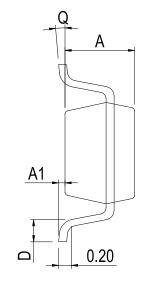




Dimensions In Millimeters(SOT-23-5)												
Symbol:	A	A1	В	С	C1	D	Q	а	b	е		
Min:	1.05	0.00	2.82	2.65	1.50	0.30	0°	0.30		1.90 BSC		
Max:	1.15	0.15	3.02	2.95	1.70	0.60	8°	0.40	0.95 BSC			

SC70-5





Dimensions In Millimeters(SC70-5)												
Symbol:	A	A1	В	С	C1	D	Q	а	b	е		
Min:	0.90	0.00	2.00	2.15	1.15	0.26	0°	0.15	0.65	1.30 BSC		
Max:	1.00	0.15	2.20	2.45	1.35	0.46	8°	0.35	BSC	1.30 850		

http://www.hgsemi.com.cn



## **Revision History**

DATE	REVISION	PAGE
2015-3-8	New	1-15
2023-10-30	Update encapsulation type, Update Lead Temperature, Update SC70-5 Physical Dimensions	1, 3、13





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